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Reliability, Packaging, Testing, and Characterization of MEMS/MOEMS and Nanodevices VIII

Richard C. Kullberg
Rajeshuni Ramesham
Editors

28–29 January 2009
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Introduction

The reliability, packaging, testing, and characterization of MEMS/MOEMS are of paramount importance to the commercialization of these advanced and useful emerging technologies. This is the International Reliability Conference and the contributors at this conference attend from around the world. The main objective of this one and only premier reliability conference is to provide a technical forum for in-depth investigations and interdisciplinary discussions involving reliability, packaging, testing, and characterization of MEMS/MOEMS. The response to the call for papers has been awesome and technically rewarding to the MEMS/MOEMS and other community.

The Reliability, Packaging, Testing, and Characterization of MEMS/MOEMS and Nanodevices VIII conference is sponsored by SPIE, and is a part of Photonics West 2009. The conference is a part of the MOEMS-MEMS 2009 Devices/Applications/Reliability symposium and education program on MOEMS-MEMS, which was held 24–29 January 2009 in the San Jose Convention Center, San Jose, California, USA. SPIE is the premier international forum for presentation of the latest developments associated with MEMS and MOEMS including reliability, testing, packaging, materials, surfaces, and characterization. This conference on the topic of Reliability, Packaging, Testing, and Characterization has been held for over 10 consecutive years.

In preparing for the conference, 20 high-quality papers were received from various countries. This year four sessions covered MEMS Packaging: Assembly and Reliability, MEMS/MOEMS Reliability, and Testing, Characterization, and Failure Analysis of MEMS/MOEMS.

We had a technical program that has three plenary speakers and four invited/keynote speakers from various reputed laboratories around the country and the globe.

We would like to personally thank Dr. Danelle Tanner, Dr. Sonia García-Blanco, Dr. Herbert Shea, as well as Dr. Al Henning and Dr. Thomas Suleski (symposium chair and cochair), and the SPIE staff for their unstinted timely support and encouragement. Finally, we would like to thank the session chairs, conference cochairs, and the program committee members for their support in organizing this conference successfully. We thank all the participants and everyone who participated in this conference.

Richard C. Kullberg
Rajeshuni Ramesham